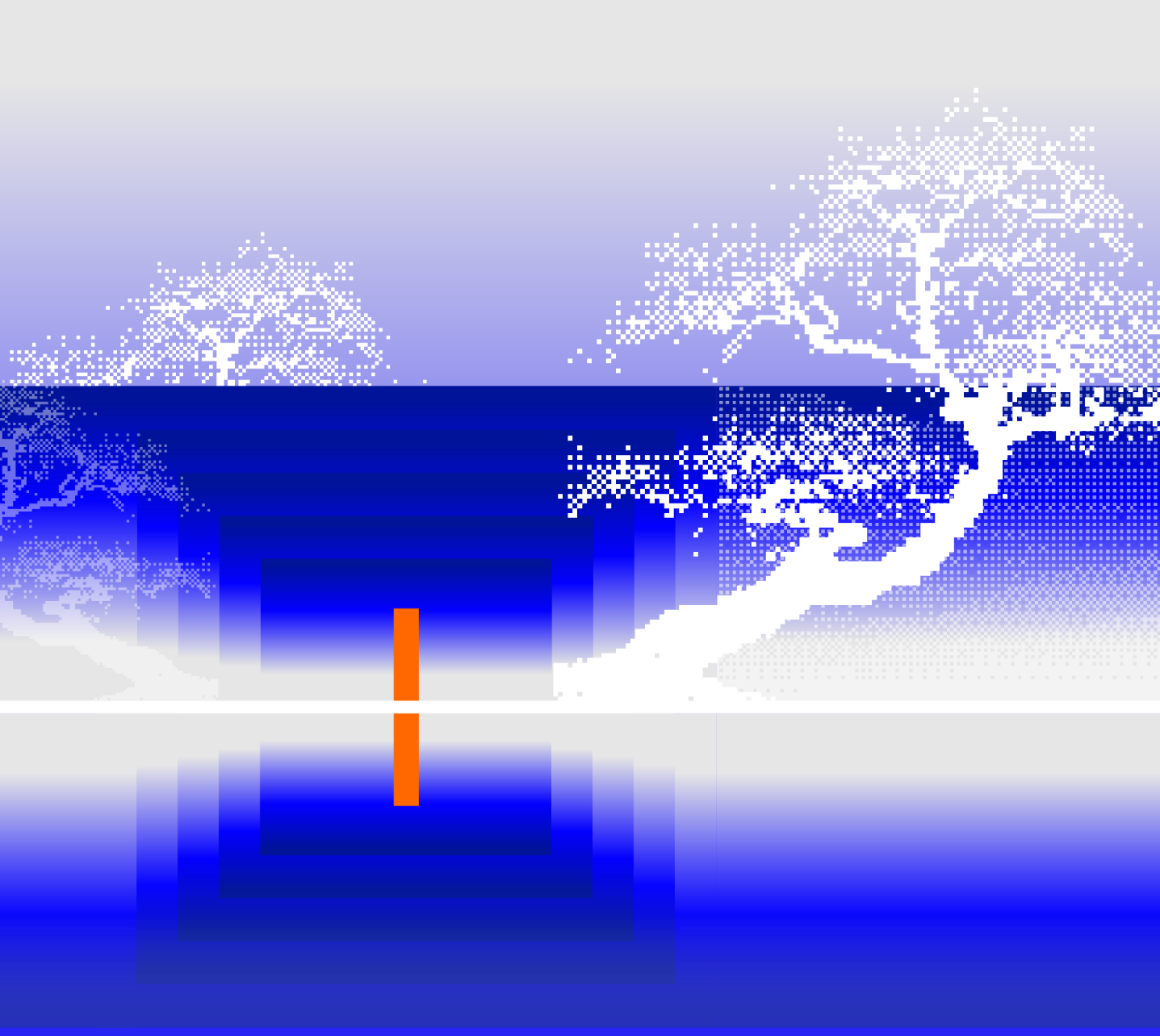

GSA®

International Summit 2026

Oct. 22
Shanghai, China

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GSA is Where Leaders Meet to establish a profitable and sustainable semiconductor ecosystem. This expanding ecosystem encompasses semiconductors, software, solutions, systems and services. As a leading semiconductor and technology industry organization, we offer an efficient and strategic platform for thought leadership.

GSA has an impressive global footprint **representing 300+ corporate members** on six continents. As a result of our unique, neutral platform, our membership ranges from the most exciting, emerging companies to semiconductor industry stalwarts and technology leaders. Our members now represent **84% of the $662B plus semiconductor industry.**



WELCOME TO THE 2026 GSA INTERNATIONAL SUMMIT

On behalf of the **Global Semiconductor Alliance,** it is my pleasure to welcome you to the 2026 GSA International Summit in Shanghai.

This Summit brings together senior executives and technology leaders from across the global semiconductor industry and broader technology community at a time when semiconductors are playing an increasingly central role in the intelligent systems transforming business and society. As these technologies continue to evolve, realizing their full potential will require not only advances in semiconductor technology, but also greater coordination across the industries that develop, deploy, and scale them.

Shanghai provides an ideal setting for these discussions. As a center for manufacturing, innovation, and technology adoption, it offers a unique perspective on how new technologies move from development to real-world application. Bringing together expertise from across regions, markets, and disciplines helps create new pathways to accelerate progress, expand markets, and strengthen global technology value chains.

Throughout the Summit, we will explore the trends, business priorities, and emerging opportunities shaping the next chapter of our industry. More importantly, we will have the opportunity to learn from one another, challenge our thinking, and build relationships that extend well beyond this event.

I encourage you to take full advantage of your time here. Equally valuable to the presentations are the conversations between sessions, the connections made over a meal, and the exchange of ideas that occurs when leaders with different perspectives come together.

I would also like to extend my sincere thanks to our sponsors and partners. Their support helps make this event possible and contributes to the meaningful engagement that distinguishes the GSA community.

Thank you for joining us in Shanghai. The insights and perspectives you bring are what make this gathering meaningful, and we look forward to the discussions and connections that will emerge from this year's Summit.



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13:00	**Registration**
13:30	**Welcome Remarks** Jodi Shelton, CEO, GSA Haijun Zhao, GSA BOD Member, Co-Chief Executive Officer, SMIC
13:40	**Agentic AI Factors Impacting Growth of Semiconductor Market and Activities of US and Chinese Companies in Agentic AI** Handel Jones, Founder and CEO, International Business Strategies (IBS) Abstract: The increased adoption of agents is resulting in high growth in demand for tokens, which is resulting in strong demand for semiconductors. The result is that there are shortages of many semiconductor products, which is expected to continue through Q1/2028. There is also growth of physical AI, including humanoid robots, smart glasses, and other areas, which has a positive impact on the semiconductor market in 2030 to 2035. There are rapid enhancements in AI capabilities, and leadership in AI will have a major impact on competitiveness in the global economy.
14:10	**From Watts to Bits: Reshaping the Value of Compute and Unlocking New Industry Opportunities In the AI Era** Feng Chen, CEO, Arm Technology (China) Co., Ltd.
14:30	**AI ASIC in the Cloud，at the Edge, on the Device** Wayne Dai, Chairman, President and CEO, VeriSilicon Abstract: With the rapid advancement of AI technology, AIGC models are creating massive computing power demands for training and inference in the cloud, as well as fine-tuning and inference at the edge. Meanwhile, as on-device AI continues developing, AI is accelerating its integration into smart devices, positioning applications such as AI glasses, AI toys, AI rings, and intelligent driving as key incremental drivers of industrial growth. Compared to cloud AI, edge and on-device AI impose more stringent requirements on chip power consumption, energy efficiency, and real-time responsiveness, and these demands, along with fast-growing personal AI agents, are creating new development opportunities for AI ASICs. This presentation will outline implementation solutions and key technical specifications of VeriSilicon's cloud, edge, and on-device AI ASIC design platforms.
14:50	**OmniConnect: Fanout Solution Addressing AI Inference Memory Wall** Dr. Haoli Qian, Chief R&D Officer, Credo

PROGRAM

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15:10	**The Impact of AI on Edge-Side Semiconductors** Dr. Youm Huh, CEO and Chairman, Silicon Mitus
15:30	**Networking Break**
16:00	**Networking for AI Data Centers: Breaking Connectivity and Power Walls** Dr. Hong Hou, President & CEO, Semtech Abstract: Global data center capex is on a trajectory to more than $2 trillion annually by the end of the decade, driven by agentic AI, inference, and enterprise adoption. Yet the binding constraint on AI infrastructure is no longer compute — it is connectivity and power. This keynote examines the AI data center network across its four connectivity domains — scale-in, scale-up, scale-out, and scale-across — and how the mix of copper and optical solutions is evolving as data rates move from 800G to 1.6T and 3.2T. It will address the growing role of linear signal integrity ("linear when you can, retimed when you must"), which cuts interconnect power by 50–60% versus DSP-retimed architectures; the emergence of new form factors such as XPO, NPO, and CPO; and why. The talk closes with a perspective on optical I/O scaling and what a co-optimized, open ecosystem of analog, photonic, and packaging technologies means for the semiconductor industry and the AI build-out ahead.
16:20	**Striding into the era of Embodied AI - How to bring Robot to the Real World** Rock Yang, Co-Founder and President, Striding AI
16:40	**Beyond AI: Connecting Intelligence to the Physical World** Ivan Lee, Co-Founder & CEO, Poncan Semiconductor Limited
17:00	**Panel Session** **Topic: "Connecting Intelligence: Semiconductor Innovation from AI Infrastructure to Physical AI"** **Moderator:** · Yu Yang, PhD, Principal Analyst, Automotive Semiconductors, Yole Group **Panelists:** · Dr. Hong Hou, President & CEO, Semtech · Wei Wang, Ph.D., Sr. Director, SITRI · TBD
17:30	**Closing Remarks**
17:35	**VIP Reception & VIP Dinner**



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Feng Chen



CEO

Arm Technology (China) Co., Ltd.

Mr. Chen Feng currently serves as the CEO of Arm Technology (China) Co., Ltd., overseeing the company's overall operations and strategic management.

As a veteran in the semiconductor industry, he possesses decades of hands-on experience and profound technical expertise in integrated circuit design. Earlier in his career at Bell Labs (USA), he pioneered R&D in mobile communication ICs and was granted multiple international patents. After returning to China in 2002, he served as Director of Design Services Department at SMIC, spearheading several national-level key R&D initiatives. Prior to joining Arm China, Mr. Chen held the position of Senior Vice President at Rockchip, where he drove significant business growth amid intense market competition.

Mr. Chen holds a Bachelor of Science in Applied Physics from Tsinghua University and a Master of Science in Electrical Engineering from Lehigh University (USA).

Haijun Zhao



Co-Chief Executive Officer

SMIC

Dr. Zhao Haijun serves as Co-Chief Executive Officer of the Company. Dr. Zhao also serves as a director of certain subsidiaries and affiliated companies of the Company. Dr. Zhao has more than 30 years of experience in semiconductor operations and technology development. Dr. Zhao served as an executive Director of the Company between 2017 and 2022, and served as the Chief Operating Officer and Executive Vice President of the Company, General Manager of SMNC from 2010 to 2016. Dr. Zhao holds a Bachelor's and a Doctor's degree in Electronic Engineering from Tsinghua University and a Master of Business Administration (MBA) degree from the University of Chicago.

Handel Jones



Founder and CEO

International Business Strategies (IBS)

Dr. Jones has over 50 years of experience in the electronics industry. He held senior management positions at ITT and other companies. At Rockwell, he was VP of Strategic Planning, Acquisitions, International Marketing, and Engineering of the Commercial Electronics Group. As VP of Engineering at Rockwell, Dr. Jones had over 1,500 engineers reporting to him, covering communications, avionics, and semiconductors. Dr. Jones was also the President and COO of a publicly traded semiconductor company. He steered the company through a successful public offering and a key acquisition.

Dr. Jones has written various books on China, including When AI Rules the World, Artificial Intelligence: How AI and IA Reshape the Future, China's Globalization (How China Becomes No. 1), and Chinamerica (McGraw-Hill).

Dr. Haoli Qian



Dr. Haoli Qian has over 20 years of communication system architect experience with deep knowledge and insights in mixed-signal architecture optimization. He is Credo's Chief R&D Officer. He previously served as the company's Vice President, Engineering. Prior to Credo, Dr. Qian was the design manager and system architect leader for Marvell Ethernet Products. He received degrees from University of Buffalo and Tsinghua University.

Chief R&D Officer

Credo

Hong Hou



President & CEO

Semtech

Dr. Hou has served as President and Chief Executive Officer of Semtech (Nasdaq: SMTC) since June 2024 and as a member of the Semtech Board of Directors since July 2023. He also serves as an independent board member of Wolfspeed (NYSE: WOLF) since September 2025. An accomplished multinational technology executive, Dr. Hou is recognized as a global enterprise leader with a strong track record of technical and business transformation in dynamic, ultra-competitive markets. He most recently served as President of the Semiconductor Group at Brooks Automation, and prior to that as Corporate Vice President and General Manager of the Cloud and Edge Networking Group at Intel Corporation (Nasdaq: INTC). He has also held executive leadership positions at Fabrinet (NYSE: FN), AXT (Nasdaq: AXTI), and Emcore (Nasdaq: EMKR), and earlier in his career held technical roles at Bell Laboratories and Sandia National Laboratories. Dr. Hou holds a Ph.D. in Electrical Engineering from the University of California, San Diego.

Ivan Lee



Co-Founder and CEO

Poncan Semiconductor

Ivan Lee is Co-Founder and CEO of Poncan Semiconductor, where he leads the company's strategy and development of advanced semiconductor solutions for high-speed optical connectivity across automotive, robotics, industrial, and broadband markets.

A seasoned semiconductor executive and technology leader, Ivan spent 12 years at Marvell Technology, serving as Vice President of the Mobile Chip Business Unit, leading multiple generations of industry-leading 3G/4G smartphone chipsets, and later as Interim CTO and Vice President of Central Engineering, overseeing critical technologies, including high-speed SerDes IP for networking products.

Previously, he held VP/GM positions at UTStarcom and began his career as an IC Design Engineer at Texas Instruments. He holds an MSEE from Georgia Tech and a BSEE from University of Texas at Austin and has received multiple industry awards.

Rock Yang



Co-Founder and President

Striding AI

Rock Yang, Co-Founder and President of Striding AI, response for global business development, Ecosystem and commercialization. Rock has 25 years of experiences of commercialization, investment and fund raising in mobile, semiconductor intelligent vehicle and AI industry. Before joining Striding AI, Rock was Chief Marketing Officer of Black Sesame Technologies (02533.HK), in charge of Marketing, fund raising and investment, Business Development and ecosystem. Prior to Black Sesame, Rock was Board Member and Vice President of Thundersoft(300496.SZ), response for Strategy, Investment and M&A, Business Development, Marketing Communication etc., and Chairman and CEO of Arm Accelerator which was the joint venture of Thundersoft and Arm at the same time. Before Thundersoft, Rock has worked with Nufront, Arm, BDA China and Panasonic on Sales and Marketing area.

Rock graduated from Precision Instrument Department, Tsinghua University. TEEC(Tsinghua Entrepreneur and Executive Club) Member.

Wayne Dai



Chairman, President and CEO

VeriSilicon

Dr. Wayne Dai founded VeriSilicon in August 2001 and has served as the chairman of the board of directors, President and Chief Executive Officer since then. Prior to founding VeriSilicon, Dr. Dai was the Co-Chairman and Chief Technology Officer of Celestry Technologies, Inc., an EDA company, which was acquired by Cadence Design Systems in 2002. Prior to that, he was the founder, chairman of the board of directors, and Chief Executive Officer of Ultima Interconnect Technology, Inc., one of the predecessor companies to Celestry.

Dr. Dai was the founding Chairman of the IEEE Multi-Chip Module Conference and IEEE Symposium on IC/Package Design Integration, Co-Chairman of the Program Committee of the 2010 International Green Energy Forum. He was an Associate Editor of IEEE Transactions on Circuits and Systems and an Associate Editor of IEEE Transactions on VLSI Systems. He has published more than 100 papers in technical journals and conferences and received the NSF Presidential Young Investigator Award from the President of United States in 1990. He was recognized as top ten venture-backed entrepreneurs and top ten talents of science and technology in China in 2005. He was honored with The Ernst & Young Entrepreneur of the Year in China in 2007. He won the ACE's Executive of the Year award in 2013, the Hurun Industry Achievement Award in 2014, the APAC Innovator of the year of WEAA in 2018, and was recognized as a "Leading Pioneer" in 2018 by Shanghai Smart City Construction, 2019 Contributor of the year and 2021 Outstanding Contributor of Industry Progress of WEAA, the 2021 Sci-Tech Innovation Golden Horse Awards Outstanding Leader award, 2023 Annual Outstanding Person of China IC Industry, and High Tech Contributor of the Year of 2023 Compass Tech Award. He is currently the Vice Chairman of Global Innovation Center, the Executive Vice President of the International Union for Science and Technology Innovation, the Vice President of the China Semiconductor Industry Association IC Design Branch, the President of the China RISC-V Industry Consortium, the Vice President and the Expert Committee Member of the Automotive Electronics Industry Alliance, the President of the Shanghai Open Processor Innovation Center, the Vice President of Shanghai Integrated Circuit Industry Association, the Vice Chairman of the Expert Committee of the Shanghai IC Industry Cluster Development Promotion Institution, and the President of Berkeley Club of Shanghai.

Dr. Dai received his B.A. degree in Computer Science and his Ph.D. degree in Electrical Engineering from the University of California at Berkeley. He was a professor in the department of Computer Engineering at the University of California at Santa Cruz.

Wei Wang, Ph.D.



Sr. Director

SITRI

Wayne Wang, Ph.D. from the Institute of Semiconductors, Chinese Academy of Sciences; Senior Director of Silicon Photonics at Shanghai Industrial μTechnology Research Institute (SITRI); Jointly Appointed Advisor at Shanghai University; Shanghai Overseas High-Level Talent; Expert of the Overall Expert Group for the Information Optoelectronics Special Project of the National Key R&D Program. He has been engaged in R&D of silicon-based optoelectronic processes and devices for over 15 years, and has published more than 80 papers in top international conferences and journals in this field, with over 30 national invention patents. As project/task leader, he has led multiple key and major national and municipal projects, and spearheaded the completion of the silicon photonics process platform construction at the Industrial uTechnology Research Institute as well as the company's external silicon photonics tape-out services.

Dr. Youm Huh



CEO and Chairman

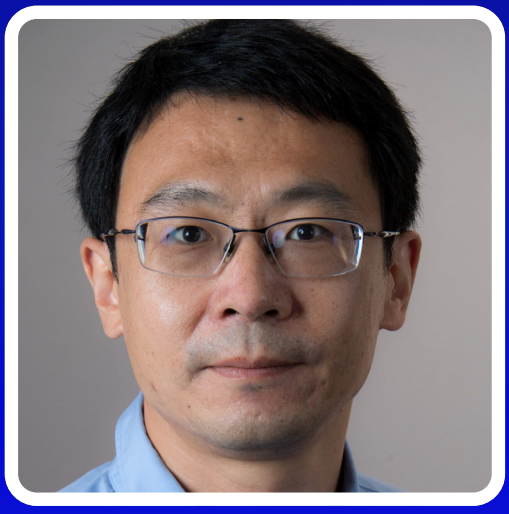
Silicon Mitus

Dr. Youm Huh is a leading figure in the Korean semiconductor industry, with more than 40 years of experience. He is the Founder and Chairman of Silicon Mitus Inc., Honorary Chairman of the Korea Fabless Semiconductor Association (KFSA), and former Vice Chairman of the Korea Semiconductor Industry Association (KSIA). He is also a Senior Member of the National Academy of Engineering of Korea (NAEK).

Previously, Dr. Huh served as the founding CEO of MagnaChip Semiconductor, which was spun off from Hynix Semiconductor in 2004. Prior to that, he served as Corporate Executive Vice President and President of the System IC Company at Hynix Semiconductor from 1997 to 2004, and as Executive Director at Samsung Electronics from 1989 to 1994.

Dr. Huh earned his Ph.D. from Stanford University, M.S. from the Korea Advanced Institute of Science and Technology (KAIST), and B.S. from Seoul National University, all in Electrical Engineering.

Yu Yang



Principal Lead Analyst,
Automotives & Robotics

Yole Group

Yu Yang, PhD is Principal Lead Analyst, Automotives & Robotics at Yole Group.

Based in Belgium, he is responsible for technology and market products, dedicated to the automotive industry and extending to humanoid robotics.

Prior to Yole Group, Dr. Yang worked as a business development partner and R&D project leader at Punch Powertrain (Belgium), R&D project manager at Bekaert (Belgium), and doctorate researcher at IMEC (Belgium).

Dr. Yang holds a PhD in materials engineering from Leuven University (Katholieke Universiteit Leuven) in Belgium and a master in electrical engineering and a bachelor in materials science & engineering both from Tsinghua University (China).

Dr. Yang serves in technical committees and advisory boards in multiple international conferences and events.

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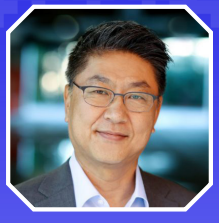

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Headquartered in Shanghai, China, SMIC Group has an international manufacturing and service base, with 8-inch and 12-inch wafer fabrication facilities in Shanghai, Beijing, Tianjin and Shenzhen. SMIC Group also has marketing and customer service offices in the U.S., Europe, Japan, and Taiwan, China.

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TSMC created the semiconductor Dedicated IC Foundry business model when it was founded in 1987. In 2023, TSMC served 528 customers and manufactured 11,895 products for various applications covering a variety of end markets including high performance computing, smartphones, the Internet of Things (IoT), automotive, and digital consumer electronics. Annual capacity of the manufacturing facilities managed by TSMC and its subsidiaries exceeded 16 million 12-inch equivalent wafers in 2023.

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BOSCH

Bosch Sensortec GmbH, a fully owned subsidiary of Robert Bosch GmbH, develops and markets a wide portfolio of microelectromechanical systems (MEMS) sensors and solutions tailored for smartphones, tablets, wearables and hearables, AR/VR devices, drones, robots, smart home and IoT (Internet of Things) applications. The product portfolio includes 3–axis accelerometers, gyroscopes and magnetometers, integrated 6– and 9–axis sensors, smart sensors, barometric pressure sensors, humidity sensors, gas sensors, optical microsystems and comprehensive software. Since its foundation in 2005, Bosch Sensortec has emerged as the MEMS technology leader in the markets it addresses. Bosch has been both a pioneer and one of the leading providers in the MEMS sensor segment since 1995 and has, to date, sold more than 26 billion MEMS sensors.
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